

Docket No. P0298US-7

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/666,399
Applicants : LEUNG et al.
Filed : September 18, 2003
TC/A.U. : 2814
Examiner : Thao X. Le
Docket No. : P0298US-7
Title: MOLDED CHIP FABRICATION AND APPARATUS


Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

NOTIFICATION OF FILING OF A CONTINUATION APPLICATION

Notification is hereby being made of the filing of a continuation application, on July 21, 2009, under application No. 12/506,989.

Respectfully submitted,

Dated: 7/24/09

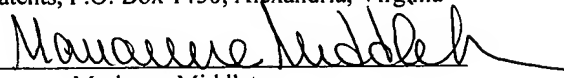

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service via First Class Mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.

7/24/09
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Marianne Middleton